

Title (en)

DEVICE FOR PACKING ELECTRONIC COMPONENTS USING INJECTION MOULDING TECHNOLOGY

Title (de)

VORRICHTUNG ZUM VERPACKEN ELEKTRONISCHER BAUTEILE MITTELS SPRITZGUSSTECHNIK

Title (fr)

DISPOSITIF D'EMBALLAGE DE COMPOSANTS ELECTRONIQUES PAR LA TECHNIQUE DE MOULAGE PAR INJECTION

Publication

EP 1259986 A2 20021127 (DE)

Application

EP 01919152 A 20010302

Priority

- DE 0100778 W 20010302
- DE 10010461 A 20000303

Abstract (en)

[origin: DE10010461A1] Process for packing electronic components comprises preparing a ceramic substrate (11) with conducting pathways (5), contact connection surfaces (6) and pressure contacts (8); preparing an injection molding tool (20) forming the housing mold; pressing the tool onto a ductile annular metal layer (13) in the edge region of the substrate; injecting a plastic composition in the hollow chamber (25) between the molding tool and the components on the first side of the substrate; applying contact outer connection surfaces in predetermined positions of a second side of the substrate; and separating the components. An Independent claim is also included for a device for packing electronic components. Preferred Features: The ceramic substrate is made from finely ground Al₂O₃ having a purity of at least 96% and containing small amounts of MgO.

IPC 1-7

H01L 23/00

IPC 8 full level

H01L 23/12 (2006.01); **H01L 21/56** (2006.01); **H01L 23/00** (2006.01); **H01L 23/13** (2006.01); **H01L 23/15** (2006.01); **H01L 23/28** (2006.01); **H01L 23/31** (2006.01); **H01L 23/498** (2006.01)

CPC (source: EP US)

H01L 21/565 (2013.01 - EP US); **H01L 23/3128** (2013.01 - EP US); **H01L 23/49816** (2013.01 - EP US); **H01L 23/49894** (2013.01 - EP US); **H01L 23/562** (2013.01 - EP US); **H01L 24/97** (2013.01 - EP US); **H01L 24/45** (2013.01 - EP US); **H01L 24/48** (2013.01 - EP US); **H01L 2224/32225** (2013.01 - EP US); **H01L 2224/451** (2013.01 - EP US); **H01L 2224/48091** (2013.01 - EP US); **H01L 2224/48227** (2013.01 - EP US); **H01L 2224/73265** (2013.01 - EP US); **H01L 2224/97** (2013.01 - EP US); **H01L 2924/00014** (2013.01 - EP US); **H01L 2924/01004** (2013.01 - US); **H01L 2924/01005** (2013.01 - EP US); **H01L 2924/01006** (2013.01 - EP US); **H01L 2924/01012** (2013.01 - EP US); **H01L 2924/01013** (2013.01 - EP US); **H01L 2924/0102** (2013.01 - EP US); **H01L 2924/01029** (2013.01 - EP US); **H01L 2924/01032** (2013.01 - EP US); **H01L 2924/01033** (2013.01 - EP US); **H01L 2924/01057** (2013.01 - EP US); **H01L 2924/01068** (2013.01 - EP US); **H01L 2924/01078** (2013.01 - EP US); **H01L 2924/01082** (2013.01 - EP US); **H01L 2924/09701** (2013.01 - EP US); **H01L 2924/12041** (2013.01 - EP US); **H01L 2924/14** (2013.01 - EP US); **H01L 2924/15311** (2013.01 - EP US); **H01L 2924/15787** (2013.01 - EP US); **H01L 2924/181** (2013.01 - EP US); **H01L 2924/19041** (2013.01 - EP US); **H01L 2924/30107** (2013.01 - EP US); **H01L 2924/3511** (2013.01 - EP US)

C-Set (source: EP US)

EP

1. **H01L 2224/48091 + H01L 2924/00014**
2. **H01L 2224/97 + H01L 2224/85**
3. **H01L 2224/97 + H01L 2924/15311**
4. **H01L 2224/451 + H01L 2924/00**
5. **H01L 2924/15787 + H01L 2924/00**
6. **H01L 2924/00014 + H01L 2224/45099**
7. **H01L 2924/14 + H01L 2924/00**
8. **H01L 2924/181 + H01L 2924/00012**
9. **H01L 2224/73265 + H01L 2224/32225 + H01L 2224/48227 + H01L 2924/00**
10. **H01L 2924/15311 + H01L 2224/73265 + H01L 2224/32225 + H01L 2224/48227 + H01L 2924/00**

US

1. **H01L 2224/48091 + H01L 2924/00014**
2. **H01L 2224/97 + H01L 2224/85**
3. **H01L 2224/97 + H01L 2924/15311**
4. **H01L 2224/451 + H01L 2924/00**
5. **H01L 2924/15787 + H01L 2924/00**
6. **H01L 2924/00014 + H01L 2224/45099**
7. **H01L 2924/14 + H01L 2924/00**
8. **H01L 2924/181 + H01L 2924/00012**
9. **H01L 2224/73265 + H01L 2224/32225 + H01L 2224/48227 + H01L 2924/00**

Designated contracting state (EPC)

AT BE CH CY DE FR GB LI

DOCDB simple family (publication)

DE 10010461 A1 20010913; EP 1259986 A2 20021127; JP 2003526208 A 20030902; JP 2005354095 A 20051222; JP 3847166 B2 20061115; US 2003178747 A1 20030925; US 7215010 B2 20070508; WO 0165601 A2 20010907; WO 0165601 A3 20020620

DOCDB simple family (application)

DE 10010461 A 20000303; DE 0100778 W 20010302; EP 01919152 A 20010302; JP 2001564393 A 20010302; JP 2005209309 A 20050719; US 22075202 A 20021209